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Revision. 3

MOS FET

Unit: mm

FK8V03020L

Panasonic

FK8V03020L

Silicon N-channel MOS FET

For lithium-ion secondary battery protecion circuit

■ Features

- Low drain-source On-state Resistance RDS(on) typ = 5.4 m Ω (VGS = 4.5 V)
- Halogen-free / RoHS compliant (EU RoHS / UL-94 V-0 / MSL:Level 1 compliant)
- Marking Symbol: 3B

■ Packaging

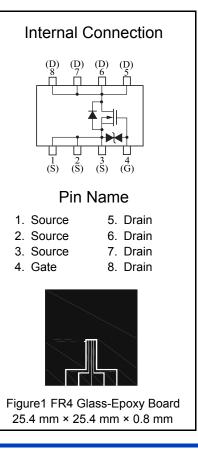
Embossed type (Thermo-compression sealing): 3 000 pcs / reel (standard)

0. 16 (0.81)0.65 5. Drain 1. Source 2. Source 6. Drain 3. Source 7. Drain 8. Drain 4. Gate WMini8-F1 Panasonic JEITA SC-115 Code

Parameter	Symbol	Rating	Unit	
Drain-source Voltage	VDS	33	V	
Gate-source Voltage	VGS	±20	V	
Drain Current (Steady State) *1	ID	14		
Drain Current (t = 10 s) *1	טו	18		
Drain Current (Pulsed) *1,*2	IDp	56	Α	
Source Current (Pulsed)	ISp	14		
(Body Diode) *1,*2	(BD)	14	1	
Total Power Dissipation (Steady State) *1	PD	1	W	
Total Power Dissipation (t = 10 s) *1	טו	1.6	V V	
Channel Temperature	Tch	150	°C	
Operating Ambient Temperature	Topr	-40 to +85	°C	
Storage Temperature Range	Tstg	-55 to +150	°C	
Avalanche Current *3	lar	60	Α	

Note: *1 Device mounted on a glass-epoxy board (See Figure 1)

- *2 Pulse test: Ensure that the channel temperature does not exceed 150°C
- *3 Conditions: VDS = 24 V, VGS = 10 V, L = 10 μ H



Doc No. TT4-EA-13637

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■ Electrical Characteristics Ta = 25°C ± 3°C

Static Characteristics

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Drain-source Breakdown Voltage	VDSS	ID = 1 mA, VGS = 0 V	33			V
Zero Gate Voltage Drain Current	IDSS	VDS = 33 V, VGS = 0 V			1	μΑ
Gate-source Leakage Current	IGSS	$VGS = \pm 16 \text{ V}, VDS = 0 \text{ V}$			±10	μΑ
Gate-source Threshold Voltage		ID = 2.2 mA, VDS = 10 V	1.0		3.0	V
Duain assuras On atata Basistanas *1		ID = 7A, VGS = 10 V		3.6	4.6	mΩ
Drain-source On-state Resistance	RDS(on)2	ID = 7A, VGS = 4.5 V		5.4	9.8	

Dynamic Characteristics

Input Capacitance	Ciss	VDC 10.V VCC 0.V	1500)	
Output Capacitance	Coss	VDS = 10 V, VGS = 0 V f = 1 MHz	300		pF
Reverse Transfer Capacitance	Crss	1 = 1 1011 12	200		
Turn-on Delay Time *2	td(on)	VDD = 15 V, VGS = 0 to 10 V	10		
Rise Time *2	tr	ID = 7 A	5		ns
Turn-off Delay Time *2	td(off)	VDD = 15 V, VGS = 10 to 0 V	200		113
Fall Time *2	tf	ID = 7 A	150		
Total Gate Charge	Qg	VDD = 15 V, VGS = 0 to 4.5 V,	14		
Gate-source Charge	Qgs	ID = 14 A	4		nC
Gate-drain Charge	Qgd		6		

Body	y Diode	Characteristic
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Body Diode Characteristic					
Diode Forward Voltage *1	VSD	IS = 7 A, VGS = 0 V	0.8	1.2	V

Note: 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 Measuring methods for transistors.

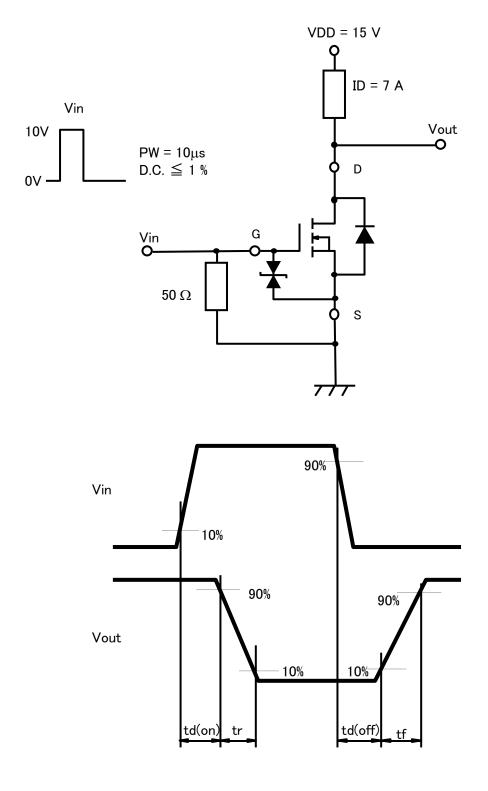
Page 2 of 6

Established: 2011-06-03 : 2013-10-15 Revised

^{2. *1} Pulse test: Ensure that the channel temperature does not exceed 150°C

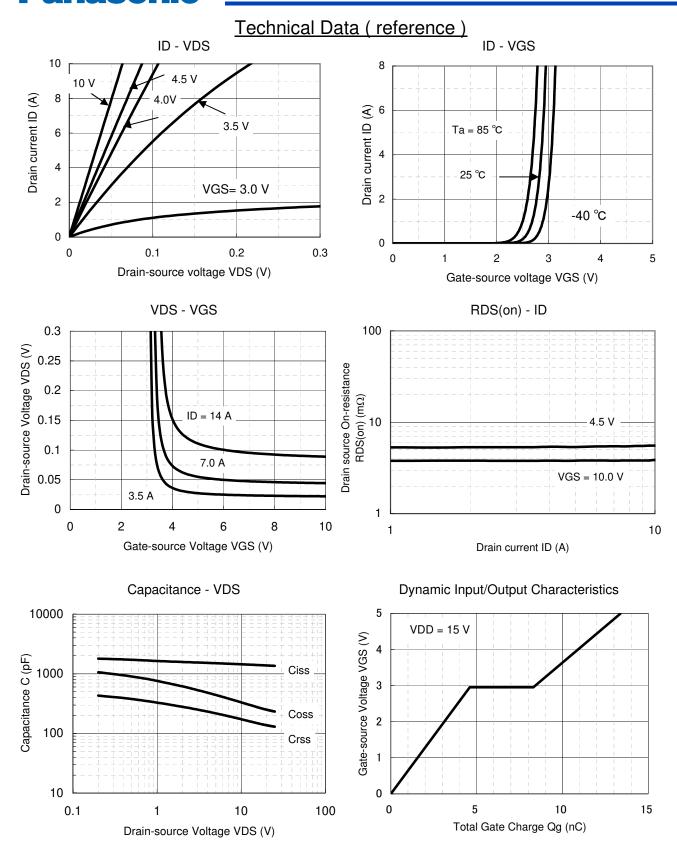
^{*2} Measurement circuit for Turn-on Delay Time/Rise Time/Turn-off Delay Time/Fall Time

*2 Measurement circuit for Turn-on Delay Time/Rise Time/Turn-off Delay Time/Fall Time



Panasonic

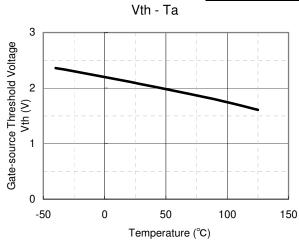
MOS FET FK8V03020L

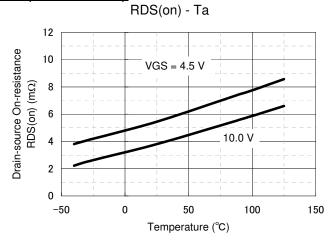


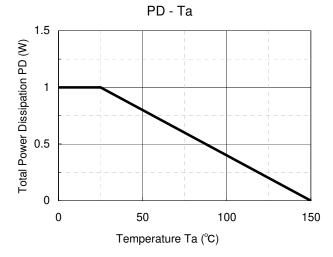
Panasonic

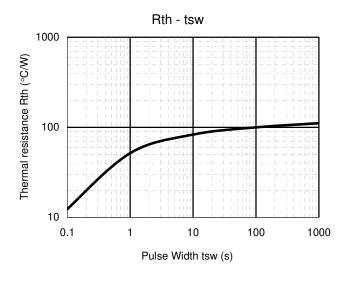
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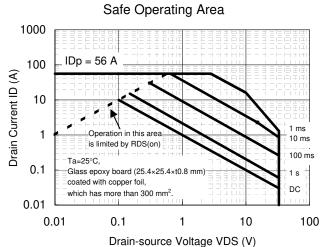
Technical Data (reference)











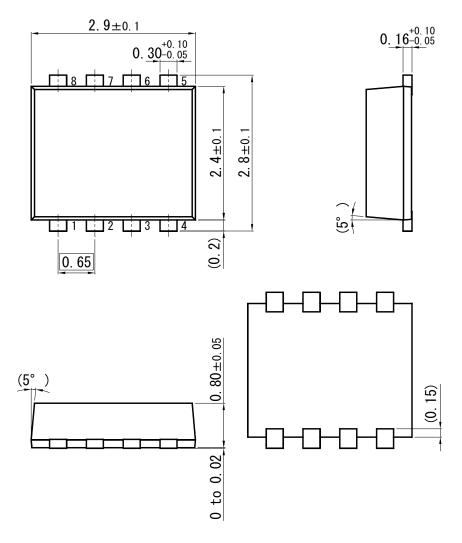
Page 5 of 6

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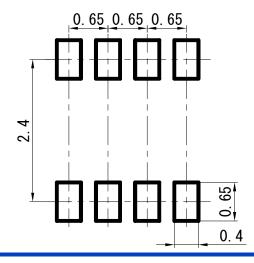
MOS FET FK8V03020L

WMini8-F1

Unit: mm



■ Land Pattern (Reference) (Unit : mm)



Page 6 of 6

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